

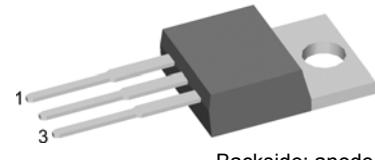
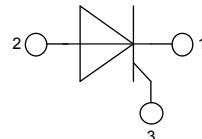
Standard SCR

Single Thyristor

V_{RRM} = 1600 V
I_{T(RMS)} = 47 A
I_{T(AV)M} = 30 A

Part number

CMA 30 E 1600 PB



Backside: anode

Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability of blocking currents and voltages

Applications:

- Motor control
- Power converter
- AC power controller
- Switch mode and resonant mode power supplies
- Light and temperature control

Package:

- Housing: TO-220
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	Unit
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1700	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1600	V
I_{RD}	reverse current, drain current	$V_R = 1600\text{ V}$ $V_R = 1600\text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		10 2	μA mA
V_T	forward voltage	$I_F = 30\text{ A}$ $I_F = 60\text{ A}$ $I_F = 30\text{ A}$ $I_F = 60\text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1.45 1.70 1.40 1.65	V
$I_{T(AV)M}$	max. average forward current	$T_C = 115^\circ\text{C}$	$T_{VJ} = 150^\circ\text{C}$		30	A
$I_{T(RMS)}$	RMS forward current	180° sine			47	A
V_{TO} r_T	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ\text{C}$		0.92 18	V $\text{m}\Omega$
R_{thJC}	thermal resistance junction to case				0.75	K/W
T_{VJ}	virtual junction temperature			-40	150	$^\circ\text{C}$
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$		165	W
P_{GM}	max. gate power dissipation	$t_p = 30\text{ }\mu\text{s}$ $t_p = 300\text{ }\mu\text{s}$	$T_C = 150^\circ\text{C}$		10 5 0.5	W
P_{GAV}	average gate power dissipation					
I_{FSM}	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{sine}$ $t = 8,3\text{ ms}; (60\text{ Hz}), \text{sine}$ $t = 10\text{ ms}; (50\text{ Hz}), \text{sine}$ $t = 8,3\text{ ms}; (60\text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0\text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0\text{ V}$		260 280 220 240	A
I^{2t}	value for fusing	$t = 10\text{ ms}; (50\text{ Hz}), \text{sine}$ $t = 8,3\text{ ms}; (60\text{ Hz}), \text{sine}$ $t = 10\text{ ms}; (50\text{ Hz}), \text{sine}$ $t = 8,3\text{ ms}; (60\text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0\text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0\text{ V}$		340 325 240 240	A^2s A^2s A^2s A^2s
C_J	junction capacitance	$V_R = 400\text{ V}$ $f = 1\text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$	13		pF

		Ratings			
Symbol	Definition	Conditions	min.	typ.	max.
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 125^\circ C$ repetitive, $I_T = 40 A$ $f = 50 \text{ Hz}; t_p = 200 \mu s$ $I_G = 0.2 A; di_G/dt = 0.2 A/\mu s$ $V_D = \frac{2}{3} V_{DRM}$ non-repetitive, $I_T = 22 A$			150 500 A/ μs
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ C$ $R_{GK} = \infty$; method 1 (linear voltage rise)			500 V/ μs
V_{GT}	gate trigger voltage	$V_D = 6 V$ $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$			1.3 1.6 V
I_{GT}	gate trigger current	$V_D = 6 V$ $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$			28 50 mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 150^\circ C$			0.2 V
I_{GD}	gate non-trigger current				1 mA
I_L	latching current	$t_p = 10 \mu s$ $T_{VJ} = 25^\circ C$ $I_G = 0.2 A; di_G/dt = 0.2 A/\mu s$			90 mA
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$ $T_{VJ} = 25^\circ C$			60 mA
t_{gd}	gate controlled delay time	$V_R = \frac{1}{2} V_{DRM}$ $T_{VJ} = 25^\circ C$ $I_G = 0.5 A; di_G/dt = 0.5 A/\mu s$			2 μs
t_q	turn-off time	$V_R = 100 V$; $I_T = 22 A$ $T_{VJ} = 25^\circ C$ $V_D = \frac{2}{3} V_{DRM}; t_p = 200 \mu s$ $di/dt = 10 A/\mu s; dv/dt = 20 V/\mu s$		150	μs

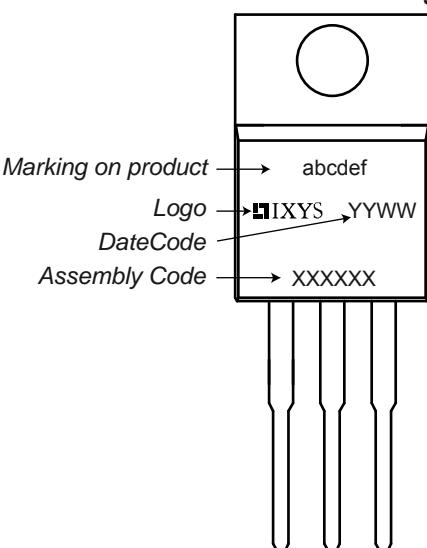
Ratings			
Symbol	Definition	Conditions	
			min.
I_{RMS}	RMS current	per pin ¹⁾	50
R_{thCH}	thermal resistance case to heatsink		0.50
T_{stg}	storage temperature	-55	150
Weight			2
M_D	mounting torque	0.4	0.6
F_c	mounting force with clip	20	60
			Nm N

¹⁾ I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

Part number

Product Marking

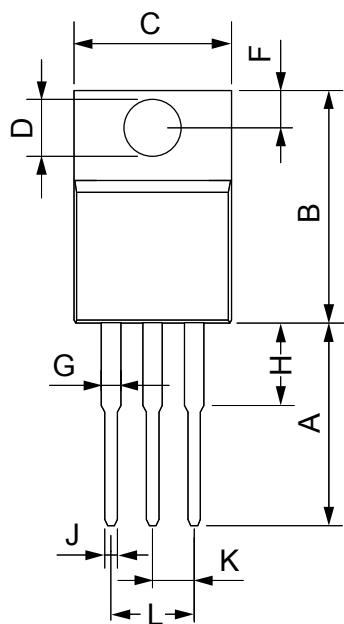


C = Thyristor (SCR)
M = Standard SCR
A = (up to 1800V)
30 = Current Rating [A]
E = Single Thyristor
1600 = Reverse Voltage [V]
PB = TO-220AB (3)

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	CMA 30 E 1600 PB	CMA30E1600PB	Tube	50	503348

Similar Part	Package	Voltage class
CMA30E1600PN	TO-220ABFP (3)	1600
CLA30E1200PB	TO-220AB (3)	1200
CS22-12io1M	TO-220ABFP (3)	1200
CS29-12io1C	ISOPLUS220AB (3)	1200
CLA30E1200PC	TO-263AB (D2Pak)	1200
CLA30E1200HB	TO-247AD (3)	1200
CS22-08io1M	TO-220ABFP (3)	800
CS29-08io1C	ISOPLUS220AB (3)	800

Outlines TO-220



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	12.70	13.97	0.500	0.550
B	14.73	16.00	0.580	0.630
C	9.91	10.66	0.390	0.420
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.230	0.270
F	2.54	3.18	0.100	0.125
G	1.15	1.65	0.045	0.065
H	2.79	5.84	0.110	0.230
J	0.64	1.01	0.025	0.040
K	2.54	BSC	0.100	BSC
M	4.32	4.82	0.170	0.190
N	1.14	1.39	0.045	0.055
Q	0.35	0.56	0.014	0.022
R	2.29	2.79	0.090	0.110